

## M-QFN Series Open Cavity Package Customer Questionnaire

Return completed to: info@MirrorSemi.com

Date:\_\_\_\_\_

## Customer Contact:

1	Customer:		
2	Contact:	Engineer Buyer	Student
3	Tel		
4	Email		

### Die Information:

5	Die size:	x	Y	z	🗌 mm 🔲 Mil 🔲 um
6	Down bonding:	🗌 Yes 🗌 No	Other:		

## Package Requirement:

7	Pins (I/0)	Min Max	Lead count is flexible Must be exact
8	Pitch	Any available 0.4mm	0.5mm 🔲 0.65mm 🗌 0.8mm 🗌 Other:
9	Rody size	Any body size that supports d	ie size Specific board footprint
	Body size	Preferred Size:~~	mm Specific socket size

#### Lid Requirement:

10	Attach:	No lid required	Permaner	nt 🗌 Tem	porary (Removable)		
	Shape:	Flat Lid	Dome Lid	Dome	e Z-axis height Min	Max	
	Material:	Any material OK	Plastic	Ceramic	Rogers RO4003C	Glass	Metal
	Color:	Any color OK	🗌 White	Black	Other:		

## Assembly:

11	Wire bonding:	Gold Wire	Aluminum wire	
12	Package Assembly:	By customer	By Subcontractor	Other:

### Application:

13	MEMS	Analog	Sensor	RF Microwave Frequency (Max):
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## Mounting:

14	Solder on PCB	RoHS Pb-Free	SnPb Non-RoHS	Other:
14	Socket mount	_YesNo 🗌 Do al	ready have socket?	Qty of sockets needed?

# Delivery and Quantities:

15	Delivery	Urgent 1-2 weeks 3-4 weeks 5-10 weeks Over 12 weeks
	Quantity	Minimum lot Quantity now: ~ Yearly quantity: